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(57) Abstract :
A wafer defect inspection device characterizes a telescopic platform 1 having polar co-ordinates installed within a housing 4 to accommodate a wafer 2 fabricated within multiple dies, the platform 1 extends/retracts in accordance to dimensions of wafer 2, a motor 3 embedded between platform 1 and housing 4 for providing rotational movement to the platform 1, a laser light emitting unit 5 installed on a guiding rack via a lead screw arrangement 6 for projecting laser light over one of die during rotation and simultaneously emits light over another die, a charge couple module 7 in sync with laser light emitting captures reflected light to digital signal processing unit 8 for determining defects in die, an artificial intelligence image capturing module 9 captures multiple images of dies for determining location of each die which is displayed over the display panel 10.

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